

IN THE CLAIMS:

Claims 8, 9, 11, 12, 14, 15, 17 through 20, and 24 have been amended herein. Claims 22 and 23 have been canceled. All of the pending claims 8 through 21 and 24 are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as amended.

Listing of Claims:

- 1-7. (Canceled)
8. (Currently Amended) An electronic device package comprising:
a transparent substrate;
a plurality of conductive traces ~~formed~~ positioned on a surface of the transparent substrate, each
conductive trace of the plurality of conductive traces having a first attachment point and a
second attachment point;
~~an optically~~ a plurality of optically interactive electronic device devices, each optically interactive
electronic device having at least one bond ~~pad~~ pad, ~~the optically interactive electronic~~
~~device and~~ mounted to the transparent substrate by a bond between the first attachment
point of aof an associated conductive trace of the plurality of conductive traces and the at
least one bond pad;
a plurality of backing cap caps, each backing cap covering a back surface of ~~the each~~ optically
interactive electronic device and device, the backing cap having at least one backing cap
attachment point on a surface thereof in electrical communication with the second
attachment point of the associated conductive trace and at least one attachment pad on a
surface another surface of the backing cap in electrical communication with the at least
one backing cap attachment ~~point; and point.~~
~~wherein the transparent substrate comprises a single substrate having multiple optically~~
~~interactive electronic devices mounted thereto.~~

9. (Currently Amended) An electronic device package comprising:

a transparent substrate;

~~a secondary~~ at least one substrate secured by a first surface thereof to a surface of the transparent substrate having a central aperture covered by the transparent substrate and a plurality of conductive traces ~~formed~~ positioned on the at least one secondary substrate around the central aperture, each conductive trace of the plurality of conductive traces having a first attachment point and a second attachment point on a second surface of the at least one secondary substrate;

an optically interactive electronic device having at least one bond pad, the optically interactive electronic device mounted to the at least one secondary substrate by a bond between the first attachment point of a conductive trace of the plurality of conductive traces and the at least one bond pad; and

a backing cap covering a back surface of the optically interactive electronic device, the backing cap having at least one backing cap attachment point on a surface thereof in electrical communication with the second attachment point of the conductive trace and at least one attachment pad ~~on a surface~~ on another surface of the backing cap in electrical communication with the at least one backing cap attachment point.

10. (Original) The electronic device package according to claim 9, further comprising:

a bond between the at least one backing cap attachment point and the second attachment point of the conductive trace, the bond comprising one of a conductive or conductor-filled epoxy, a solder joint and a layer of anisotropically conductive adhesive material.

11. (Currently Amended) The electronic device package according to claim 9, further comprising:

an array of attachment pads on the another surface of the backing cap, ~~the array of attachment pads positioned adjacent four edges of an outer perimeter of the another surface of the backing cap.~~

12. (Currently Amended) The electronic device package according to claim 9, further comprising:
a discrete conductive element disposed on the at least one attachment pad on the another surface of the backing cap.

13. (Original) The electronic device package according to claim 12, wherein the discrete conductive element comprises one of a solder ball, a solder column, a conductive epoxy, and a conductor-filled epoxy.

14. (Currently Amended) The electronic device package according to claim 9, wherein the secondary substrate comprises one of a printed circuit board, a polyimide ~~film~~film, a ~~ceramic~~ceramic, and silicon.

15. (Currently Amended) The electronic device package according to claim 9, wherein an outside perimeter of the at least one secondary substrate is substantially equal to an outside perimeter of the transparent substrate.

16. (Original) The electronic device package according to claim 9, wherein the optically interactive electronic device comprises an image sensor.

17. (Currently Amended) The electronic device package according to claim 9, wherein the at least one secondary substrate comprises a plurality of secondary substrates, each secondary substrate of the plurality secured to the surface of the transparent substrate, and the at least one optically interactive device comprises a plurality of optically interactive devices.
~~transparent substrate comprises a single substrate having a plurality of optically interactive electronic devices mounted thereto.~~

18. (Currently Amended) The electronic device package according to claim 8, further comprising:
a bond between the at least one backing cap attachment point and the second attachment point of

the associated conductive trace, the bond comprising one of a conductive or conductor-filled epoxy, a solder joint and a layer of anisotropically conductive adhesive material.

19. (Currently Amended) The electronic device package according to claim 8, further comprising:
an array of attachment pads on the another surface of the backing ~~cap~~, the array of attachment pads positioned adjacent four edges of an outer perimeter of the another surface of the backing cap.

20. (Currently Amended) The electronic device package according to claim 8, further comprising:
a discrete conductive element disposed on the at least one attachment pad on the another surface of the backing cap.

21. (Previously Presented) The electronic device package according to claim 20, wherein the discrete conductive element comprises one of a solder ball, a solder column, a conductive epoxy, and a conductor-filled epoxy.

22. (Canceled)

23. (Canceled)

24. (Currently Amended) The electronic device package according to claim 8, wherein the plurality of optically interactive electronic ~~device comprises~~ devices comprise a plurality of image sensors. ~~an image sensor.~~